

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

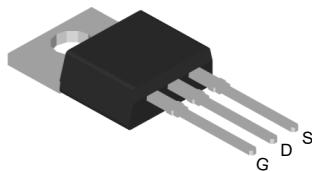
Product Summary



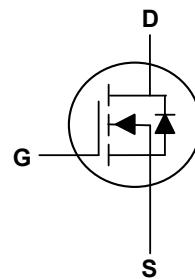
V_{DS}	30	V
I_D	90	A
$R_{DS(ON)}$ (at $V_{GS}=10V$)	6	mΩ
$R_{DS(ON)}$ (at $V_{GS}=4.5V$)	9	mΩ

Applications

- High Frequency Point-of-Load, Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch



TO-220 Top View



Absolute Maximum Ratings($T_c=25^\circ C$, unless otherwise noted)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current, $V_{GS} @ 10V^1$	$I_D @ T_c = 25^\circ C$	90	A
Continuous Drain Current, $V_{GS} @ 10V^1$	$I_D @ T_c = 100^\circ C$	58	A
Pulsed Drain Current ²	I_{DM}	180	A
Single Pulse Avalanche Energy ³	EAS	115	mJ
Avalanche Current	I_{AS}	48	A
Total Power Dissipation ⁴	$P_D @ T_c = 25^\circ C$	74	W
Storage Temperature Range	T_{STG}	-55 to 150	°C
Operating Junction Temperature Range	T_J	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Thermal Resistance Junction-Ambient ¹ (Steady State)	$R_{\theta JA}$	---	62	°C/W
Thermal Resistance Junction-Case ¹	$R_{\theta JC}$	---	1.7	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$	30	---	---	V
Static Drain-Source On-Resistance ²	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}$, $I_D=20\text{A}$	---	5.2	6	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$, $I_D=15\text{A}$	---	7	9	$\text{m}\Omega$
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}$, $I_D=250\mu\text{A}$	1.2	1.7	2.5	V
Drain-Source Leakage Current	I_{DSS}	$V_{\text{DS}}=24\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	1	uA
		$V_{\text{DS}}=24\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=55^\circ\text{C}$	---	---	5	
Gate-Source Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
Forward Transconductance	g_{fs}	$V_{\text{DS}}=5\text{V}$, $I_D=20\text{A}$	---	43	---	S
Total Gate Charge	Q_g	$V_{\text{DS}}=15\text{V}$, $V_{\text{GS}}=4.5\text{V}$, $I_D=15\text{A}$	---	20	---	nC
Gate-Source Charge	Q_{gs}		---	7.6	---	
Gate-Drain Charge	Q_{gd}		---	7.2	---	
Turn-On Delay Time	$T_{\text{d(on)}}$	$V_{\text{DD}}=15\text{V}$, $V_{\text{GS}}=10\text{V}$, $R_G=3.3\Omega$, $I_D=15\text{A}$	---	7.8	---	ns
Rise Time	T_r		---	15	---	
Turn-Off Delay Time	$T_{\text{d(off)}}$		---	37.3	---	
Fall Time	T_f		---	10.6	---	
Input Capacitance	C_{iss}	$V_{\text{DS}}=15\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	2295	---	pF
Output Capacitance	C_{oss}		---	267	---	
Reverse Transfer Capacitance	C_{rss}		---	210	---	

Drain-Source Diode Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Continuous Source Current ^{1,5}	I_s	$V_G=V_D=0\text{V}$, Force Current	---	---	50	A
Diode Forward Voltage ²	V_{SD}	$V_{\text{GS}}=0\text{V}$, $I_s=1\text{A}$, $T_J=25^\circ\text{C}$	---	---	1	V
Reverse Recovery Time	t_{rr}	$I_F=20\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$, $T_J=25^\circ\text{C}$	---	14	---	nS
	Q_{rr}		---	5	---	nC

Note:

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $V_{\text{DD}}=25\text{V}$, $V_{\text{GS}}=10\text{V}$, $L=0.1\text{mH}$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

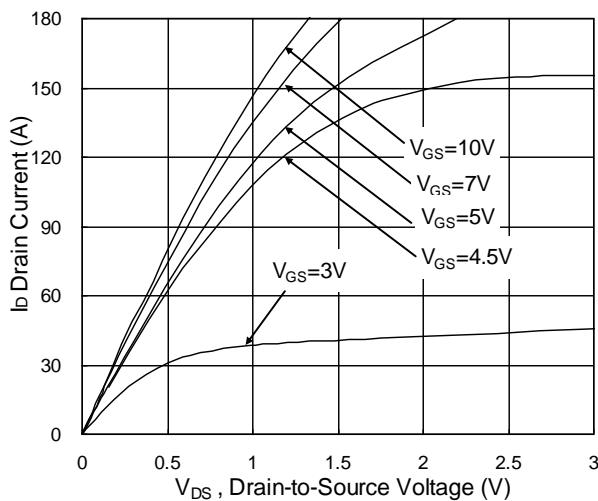


Fig.1 Typical Output Characteristics

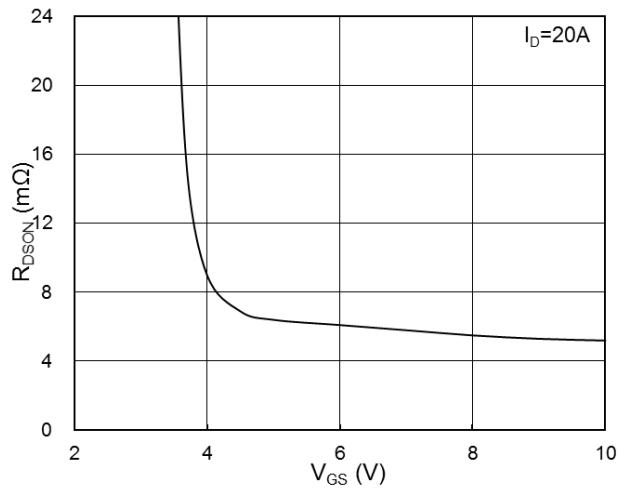


Fig.2 On-Resistance vs. G-S Voltage

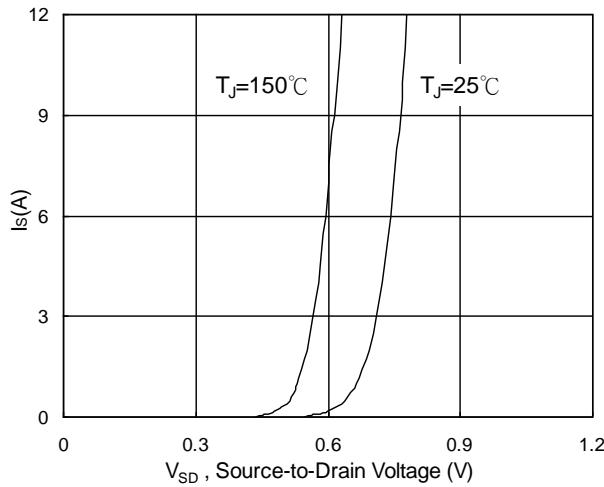


Fig.3 Source Drain Forward Characteristics

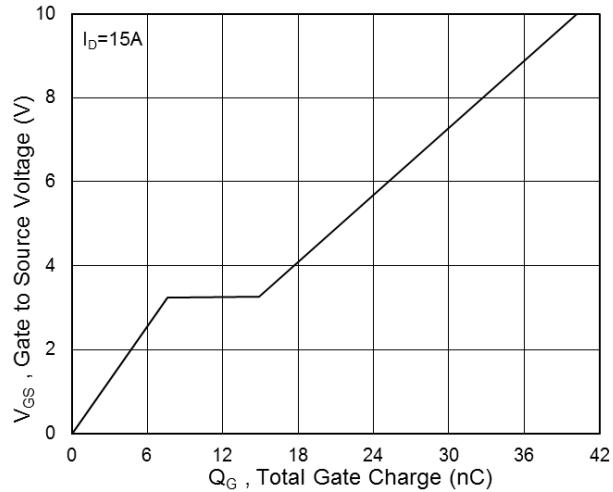


Fig.4 Gate-Charge Characteristics

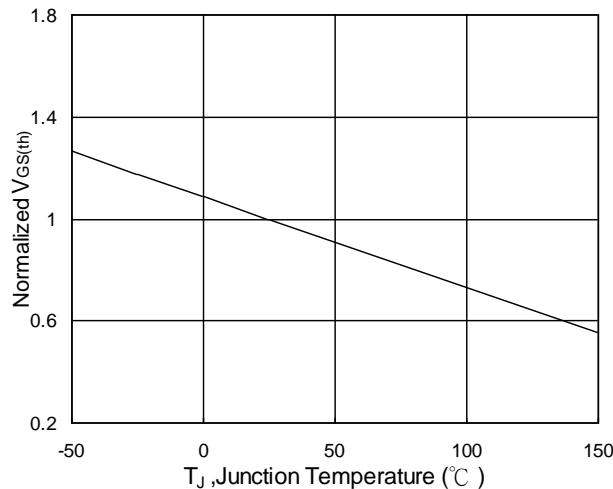


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

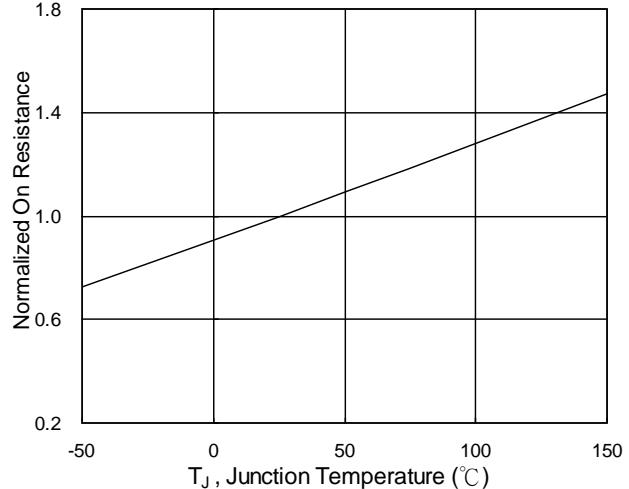
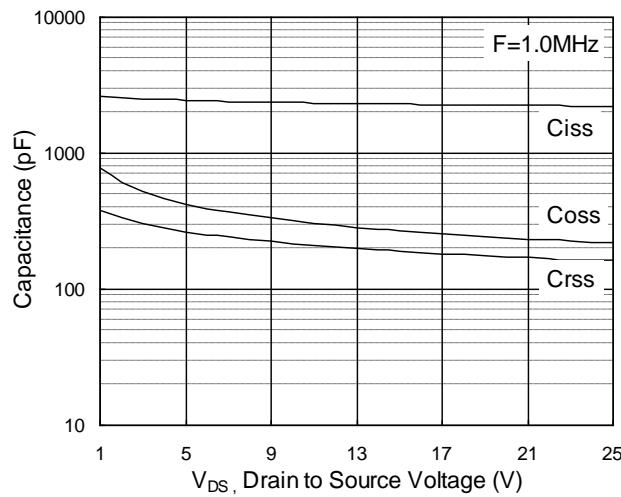
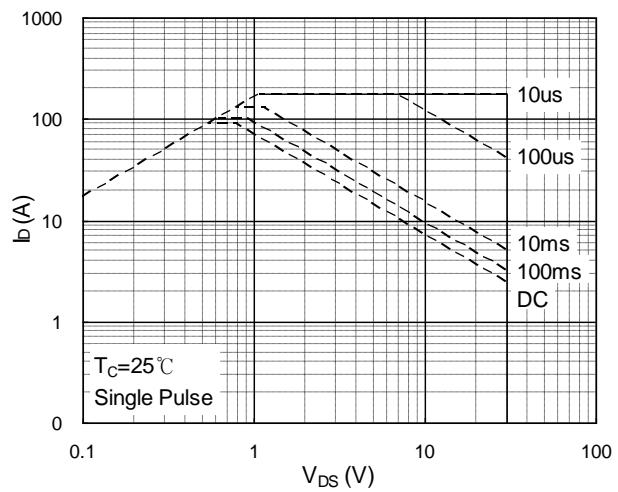
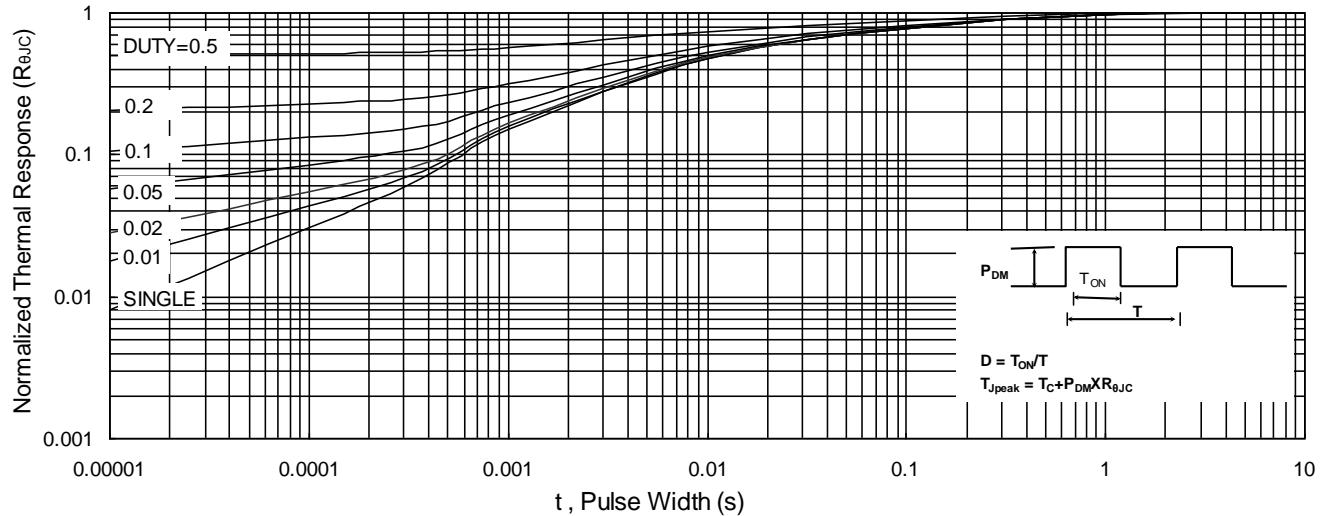
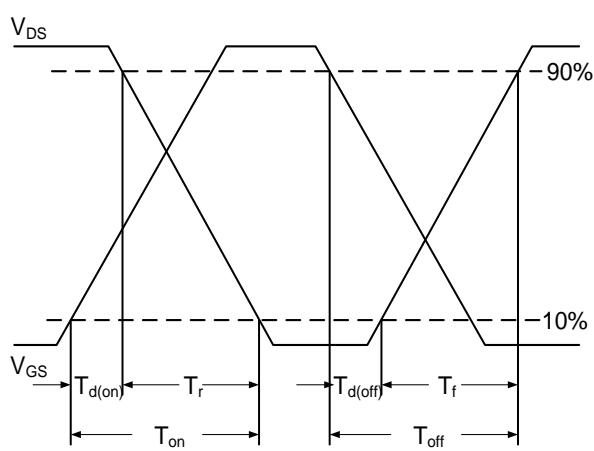
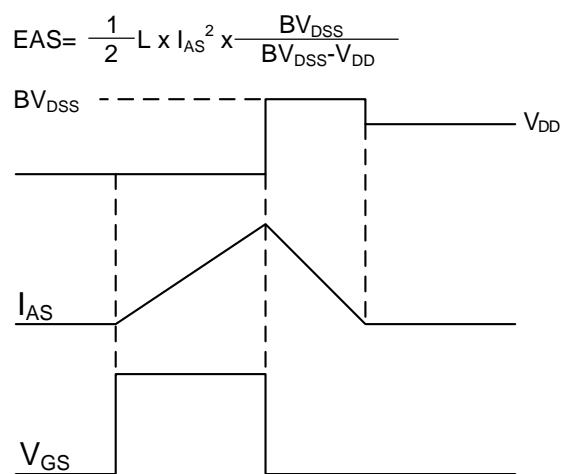
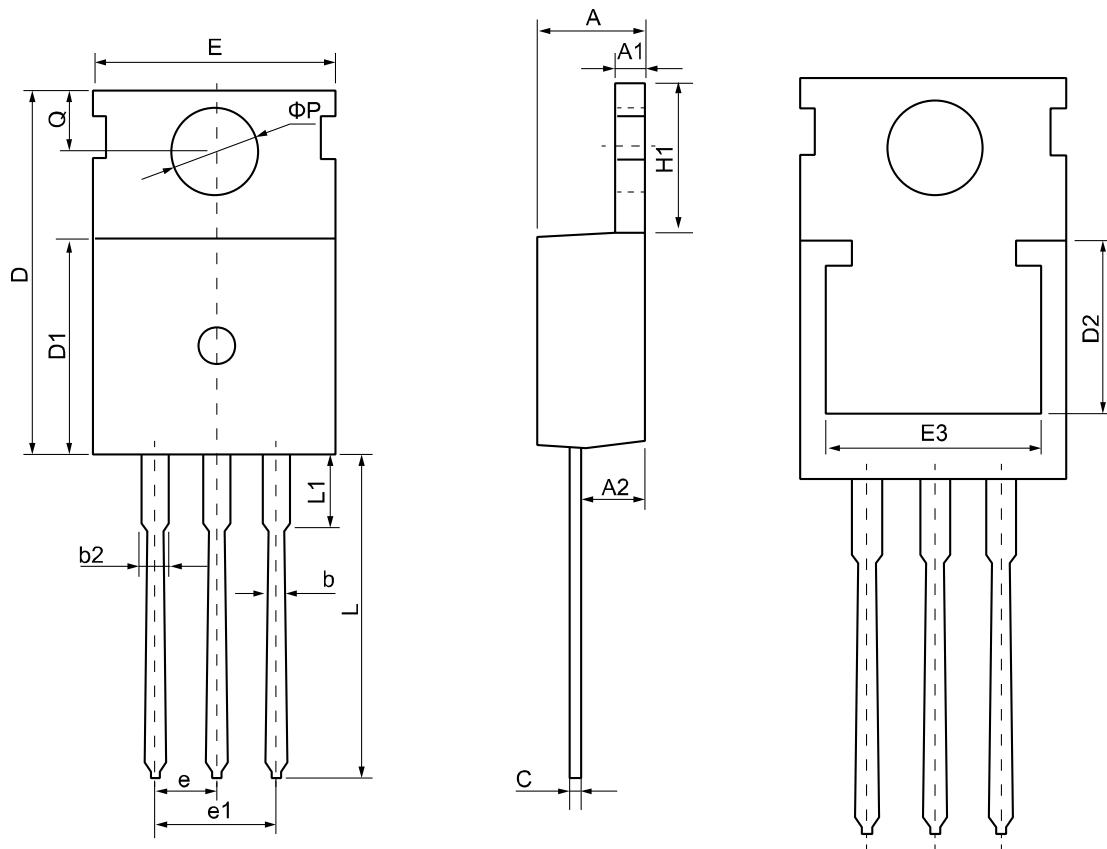


Fig.6 Normalized $R_{DS(on)}$ vs. T_J


Fig.7 Capacitance

Fig.8 Safe Operating Area

Fig.9 Normalized Maximum Transient Thermal Impedance

Fig.10 Switching Time Waveform

Fig.11 Unclamped Inductive Switching Waveform

TO-220 Package Outline Dimensions



Symbol	Dimensions (unit:mm)			Symbol	Dimensions (unit:mm)		
	Min	Typ	Max		Min	Typ	Max
A	4.30	4.55	4.75	E	9.65	10.00	10.25
A1	1.15	1.30	1.45	E3	7.00	--	--
A2	2.20	2.40	2.60	e	2.54 BSC		
b	0.70	0.80	0.95	e1	5.08 BSC		
b2	1.17	1.27	1.47	H1	6.30	6.50	6.80
c	0.40	0.50	0.65	L	12.70	13.50	14.10
D	15.30	15.60	15.90	L1	--	3.20	3.95
D1	8.90	9.10	9.35	ΦP	3.40	3.60	3.80
D2	5.50	--	--	Q	2.60	2.80	3.00